

1 K3-F23-1115G4

Intel Core I3-1115G4



Parameter list

CPU	Intel Core I3-1115G4	3.00 GHz-4.10 GHz
Cores/Threads	2Cores/4Threads	
Cache	6MB Cache	
TDP	15W	
Architecture	Tiger Lake	
Memory	2*DDR4L slot, max support 32G	
Storage	SSD (M.2 2280 SATA)	
	Optional HDD	
Audio Card	HD Audio realtek ALC 269	
Graphics	Intel® UHD Graphics for 11th Gen Intel® Processors	
Network	10/100/1000Mbps adaptive RTL 8111H	
Extendable	WIFI+BT Module (Mini PCIE), support 4G module with available sim slot	
OS Support	Windows 10、 11	
I/O Ports	4*USB3.0、 4*USB2.0、 2*HDMI、 2*DP、 1*RJ45、 1*DC、 1*MIC-IN、 1*LINE-OUT、 1*TYPE-C、 1*CLS	
Built-in socket	1.M2M KEY socket: H8.5mm supports 2280 (SATA and PCIE) 2.Battery socket: white 1*2pin (distance 1.25m) 3.M2E KEY socket: H8.5mm supports WIFI/WIFI6 4.MSATA socket: with Nano-SIM card slot (H9.0mm supports 3G/4G module) 5.2*DDR4 memory: Double D4=3200MT/S 6.Buzzer	
Boot Mode	PXE / Auto-power-on / Wake-on-LAN	
Intel Virtualization	Support	
Intel Hyper-Threading	Support	
Working Environment	Temperature: -10~60 °C	Relative Humidity: 0~95% (No Condensation)
Working Voltage	DC 12V - 5A	
Static Electriciy Storage Environment	Contact discharge 2K, Air discharge 6K	
Storage Environment	Temperature: -10~60 °C	Relative Humidity: 0~95% (No Condensation)

BIOS Function

K5-F23-1115G4

Intel Core I3-1115G4



9 10 11 12 13 14 15



2 3 4 5 6 7 8

01	POWER ON/OFF	02	USB3.0*2	03	USB3.0*2
04	Reset	05	Type-C	06	MIC
07	SPK	08	LED Indicator	09	USB2.0*2
10	RJ45 Gigabit LAN	11	USB2.0*2	12	DP
13	DP	14	HDMI*2	15	DC 12V Input
Size	L 133.8mm*W 126.6mm*H 46mm			Weight	Net : 0.65kg Gross:1.5kg

Specification

Built-in Pin	F-P1ane pin: 2*2pin (2.0 pitch) Dupont TPM pin: 14pin (2.0 pitch) SPI Fan seat: 1*4pin (1.25 pitch) with smart fan Speaker pin: 4pin (2.0 pitch) with walls USB2.0 pin: 4pin (2.0 pitch) with walls USB2.0 pin: 2*5pin (2.0 spacing) DuPont (available in dual network) SATA 3.0: Change to 2-in-1 interface, 1*12pin (1.25 pitch) according to the actual object JME and ATX-SEL: 2*3pin (2.0 pitch) ATX-DC: 4pin2.0 spacing) with walls
IC	SI0 Chip: ITE8613; Power Chip: RT3612E03; Network Card Chip: RTL8111H; Sound Card Chip: ALC269
Features	Adopting plastic top cover with aluminum alloy body; The upper cover adopts a hexagonal mesh shaped structure, with hidden air intakes and decorative strips, classic desgin
Heat Dissipation	Active cooling (air cooling)
Bracket	Dedicated bracket; Support VESA bracket
Packing Box	Kraft paper color box + Anti-fall corrugated outer box
Packing List	Power Adapter * 1 Power Cable * 1 Bracket * 1 User Manual * 1 QA Card * 1 Screws * 1